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AZ® 3300 Series Photoresists



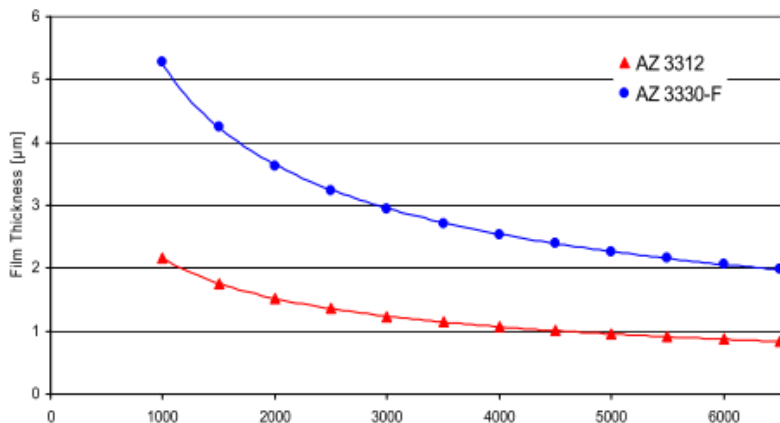
AZ 3300 Photoresists are medium resolution (0.65µm design rules), high thermal stability materials optimized for metal RIE etch or plating process environments. Fast in all exposure wavelengths between 350 and 450nm. The 3300 Series covers a coated thickness range of approximately 1.0 to 5.0µm and works well with both organic (MIF) and inorganic developers (AZ Developer or AZ 400K 1:4). Improved resolution and thermal stability vs. AZ 1500 Series.

Items in this series:

- AZ 3312 Photoresist (Gallon)
- AZ 3318D Photoresist (Gallon)
- AZ 3330F Photoresist (Gallon)

[I would like more information about AZ 3300 Photoresists!](#)

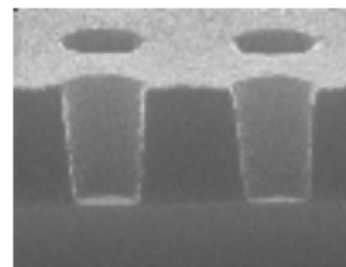
AZ 3300 Series Spin Curves



6" Si Wafers; Soft Bake 90C

Typical Process

Soft Bake: 90-105C (60s)
Expose: g-line/i-line/h-line
Post Expose Bake: 110-115C
Develop: spray, puddle or immersion
Developer: MIF recommended



0.5µm Holes in AZ 3312
1.10µm film thickness
140mJ/cm² i-line exposure
0.54NA Stepper
AZ 300MIF Develop

Authorized Distributor

**EMD
PERFORMANCE
MATERIALS**

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